CALL FOR PAPERS

ECTC OPTOELECTRONICS Program Committee

58th ECTC May 27th – May 30th, 2008
Orlando, Florida USA

Papers are solicited on all topics pertaining to the design, development, and technology of packaging optoelectronics and photonic components, devices, circuitry and systems.

Topics of interest include:

- **High Power Optoelectronics and Fiber Laser Packaging:** High-power laser diodes, bars / stacks, and Fiber lasers – including beam combining, coupling, wavelength control, hermetic packaging and thermal issues.
- **High-Brightness LED Packaging for Lighting and Commercial Applications**: Package and optical design, assembly methods, thermal management, reliability, color temperature control, phosphor materials, and volume manufacturing.
- **Optical Component Thermal Management and Reliability:** Optical component thermal management, package design, device performance, failure modes and reliability
- **Micro-optical Packaging and Manufacturing Technology:** Low cost designs, novel optics, assembly methodology and automation technology
- **Silicon Photonics Devices and Packaging:** Optical devices in Silicon, hybrid integration, FR performance, Silicon optical waveguides, photonics circuits and packaging
- **Optical Interconnects:** Integrated optics, high-speed and parallel transceivers, board-level waveguides, optical backplanes, fiber optic connectors and hybrid integration
- **Advanced Materials for Optoelectronics:** Substrates, devices, components and assembly materials

SUBMISSIONS: Please submit abstracts using the ECTC web site by **October 15, 2007**. Abstracts must comply with the guidelines outlined at the website. To have your paper considered for inclusion in the "Optoelectronics" focused sessions **YOU MUST SELECT "Optoelectronics" committee as your PRIMARY subcommittee preference** when you submit your abstract.

Please visit:

www.ectc.net

You may also submit directly to the committee chair below – please include mailing address, telephone number, FAX number and e-mail:

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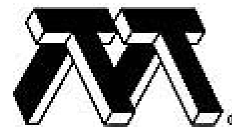
16th Conference on
Electrical Performance of Electronic Packaging
EPEP 2007

Sponsors:
IEEE Microwave Theory and Techniques Society
IEEE Components, Packaging and Manufacturing Technology Society

October 29-31, 2007

Renaissance Atlanta Hotel
Atlanta, Georgia



The general subject of the meeting is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. This meeting is the premier conference dealing with advanced and emerging issues in electrical design of interconnect structures and assurance of Signal Integrity. EPEP '07 has an outstanding technical program featuring more than 70 technical papers. The conference will feature paper sessions, a poster session and keynote speakers.

For further information, please see the web site at

www.epep.org